Flash + Controller Part Numbering System

aka e-MMC and custom card part numbers

MT FC 2G A A x M2 - xx ES

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FC= Flash + Controller

NAND Density
2G = 2GB
4G = 4GB
8G = 8GB
16G = 16GB
32G = 32GB
64G = 64GB

NAND Component

Mark	Device
A	2Gb, x8 1.8V
B	4Gb x8 3.3V
C	8Gb x8 3.3V
D	8Gb x8 3.3V
E	8Gb x8 3.3V
F	4Gb x8/x16
G	16Gb x8 3.3.V
H	32Gb x8 3.3V
J	64Gb x8 3.3V
K	32Gb x8 3.3V
L	32Gb x8 3.3V
M	16Gb x8 3.3V

Controller ID

Mark	Controller ID
A	Rev 1
B	Rev 2
C	Rev 3
D	Rev 4
E	Rev 5
F	Rev 6
G	Rev 7
H	Rev 8
I	Rev 9
J	Rev 10
K	Rev 11
L	Rev 12
M	Rev 13
N	Rev 14
P	Rev 15
Q	Rev 16
R	Rev 17
S	Rev 18
T	Rev 19
W	Rev 20
X	Rev 21

Production Status
Blank = Production
ES = Engineering Sample
MS = Mechanical Sample

Operating Temperature Range
Blank = 0°C to +70°C
WT = Standard (-25°C to +85°C)
IT = Industrial (-40°C to +85°C)
AIT = Industrial (-40°C to +85°C + HR certified test flow)

Special Options
TBD

Package Code (all packages are Pb-free)
DE = 153-ball LFBGA 11.5x13x1.4
DG = 169-ball LFBGA 12x16x1.5
DH = 169-ball LFBGA 12x18x1.4
DI = 169-ball TFBGA 12x16x1.2
DK = 169-ball LFBGA 12x16x1.4
DL = 169-ball TFBGA 12x18x1.2
DM = 153-ball TFBGA 11.5x13x1.2
DN = 169-ball LFBGA 14x18x1.4
DP = 169-ball LFBGA 14x18x1.7
DQ = 100-ball LBGA 14x18x1.4
DV = 169-ball VFBGA 12x16x1.0
EA = 153-ball WFBGA 11.5x13x0.8
EC = 169-ball WFBGA 14x18x0.8
ED = 169-ball VFBGA 14x18x1.0
EF = 169-ball TFBGA 14x18x1.2
EG = 169-ball WFBGA 12x16x0.8
EJ = 169-ball LFBGA 14x18x1.3

Reserved for Future Use

Rev. 5-2-12
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